

Novel inkjettable copper ink utilizing processing temperatures under 100 degrees C without the need of inert atmosphere

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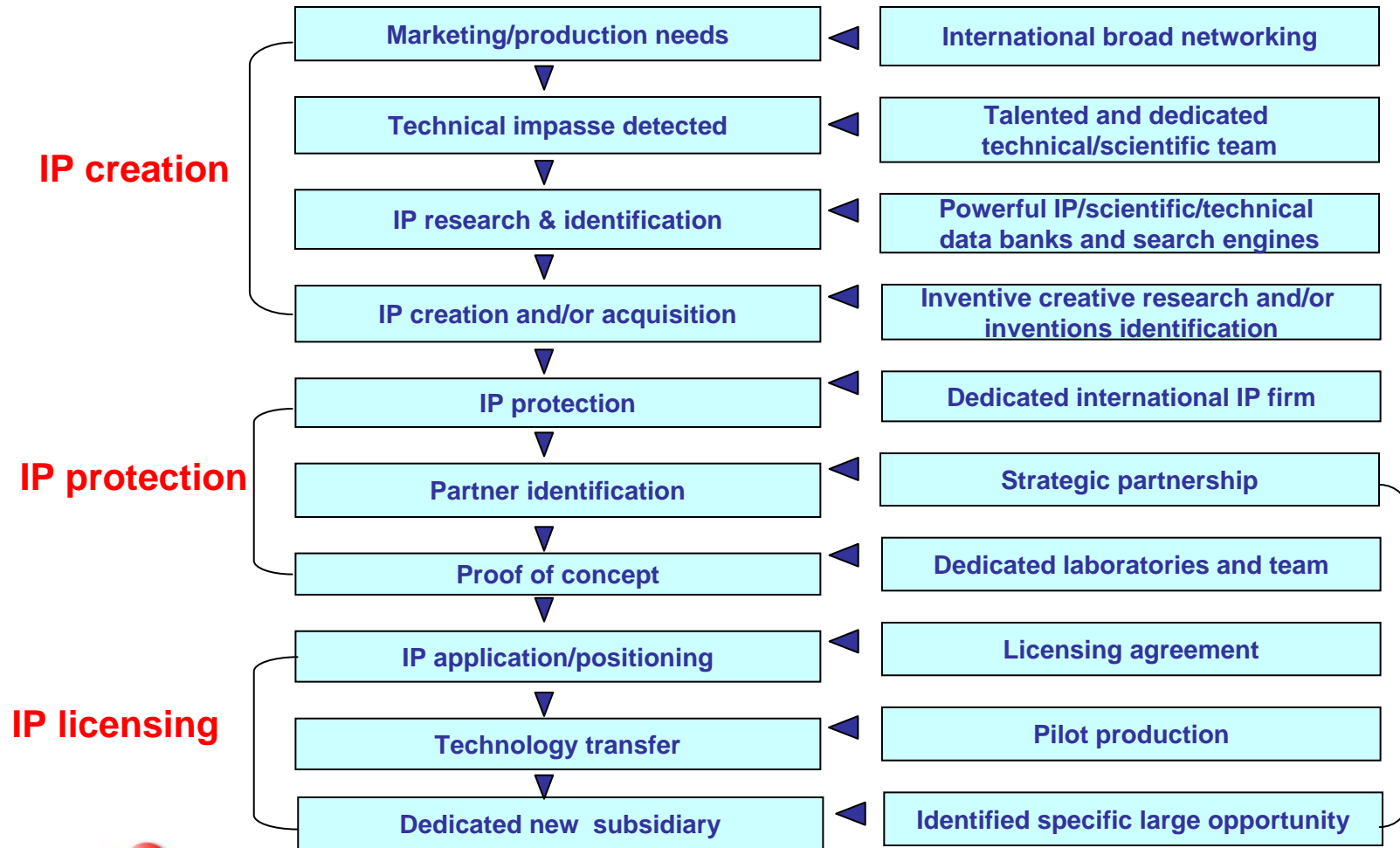
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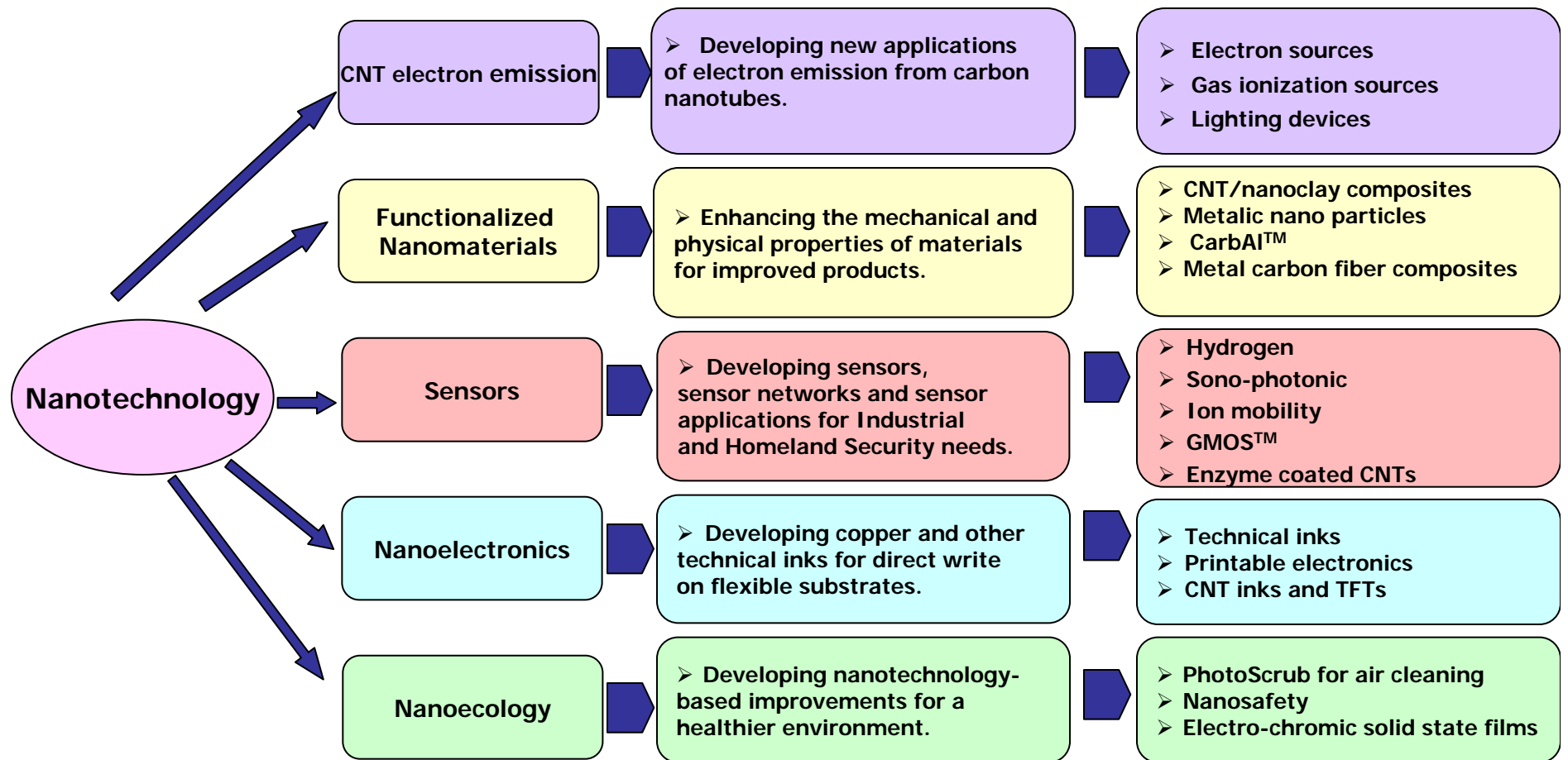
Nanotechnology definition

Nanotechnology comprises all sciences and technologies studying the processes of how two or three molecules bind together until the first aggregate of the same molecules is created achieving the same chemical/physical/biological properties as the bulk material.

How we can work with you



Current research and development activities



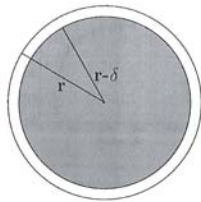
Copper nanoclusters (Cu NC)

- Number of atoms > 10
- Large variety of morphologies
- Surface/volume ratios are very important
- Cu NC are held together by metallic bonds
- Small size Cu NCs ($\sim 10^3$ atoms) show strong size dependency (quantum confinement)
- Cu NCs morphology and size play important role in solid-liquid transitions

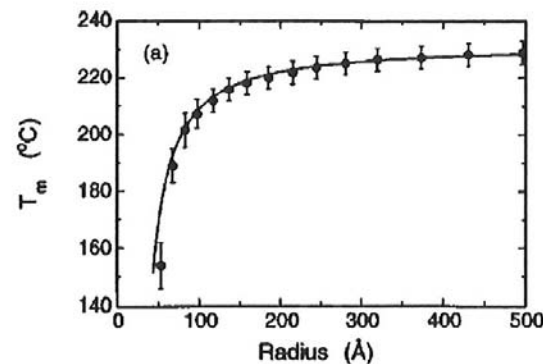
Melting point size dependency

- Generally the melting point shows a monotonic decrease with size
- Utilize the solid core/liquid shell model of melting

$$\mu_s(p, T) = \mu_l(p, T)$$



- Example

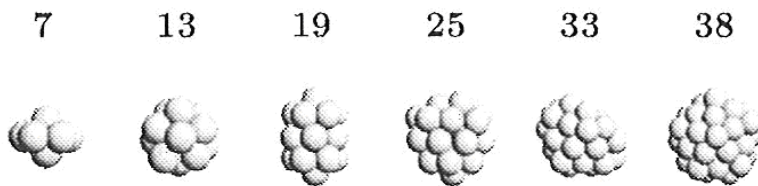


Comparison of theoretical and experimental (solid lines) melting points for tin clusters.

Copper nanoclusters formation

- The model utilized is adding single Cu atoms to a small initial seed in thermal contact with the cooler surroundings
- Important parameter: rate of temperature change

$$\frac{\partial T}{\partial t} \propto \frac{1}{R}$$



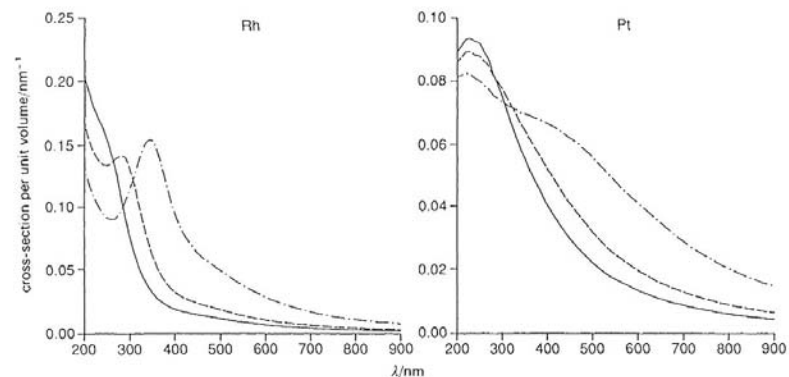
Cu₃₈ growth simulation results at T=400°K

Anomalous heat capacity of nanoparticles

- Is the result of a region of coexistence of two or more phases in the melting process
- During the melting and solidification processes single domain clusters or more complex structures with grains may form
- A lot depends on the size and structure of the initial copper nanoparticles

Absorption spectra of nanoparticles

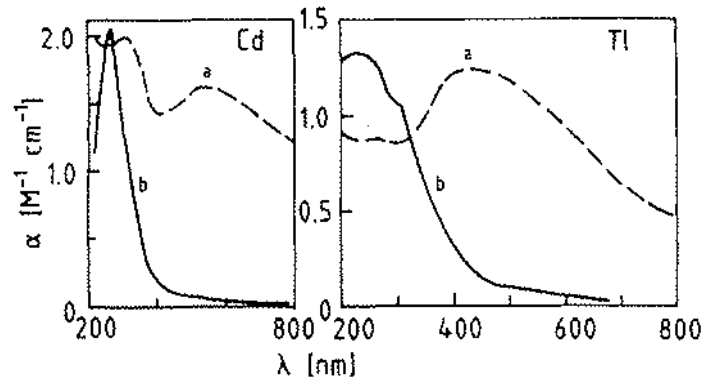
- Absorption spectra of nanoparticles is vastly different than absorption spectra of bulk material
- Absorption spectra depends on size and shape of nanoparticles
- Absorption spectra strongly related to the mean free path of the electrons in the specific material
- Example:



Absorption spectra calculated in the dipole approximation for prolate spheroidal Rh and Pt particles in water. The minor diameter of the particles is 10 nm with different aspect ratios.

Agglomeration effects

- Example:



Absorption spectra of agglomerated (a) and isolated (b) particles of cadmium and thallium in water.

Cu oxide reduction

- We found that proper UV radiation will reduce copper oxides to metallic copper (photosintering).

Targeted ink formulations for photosintering

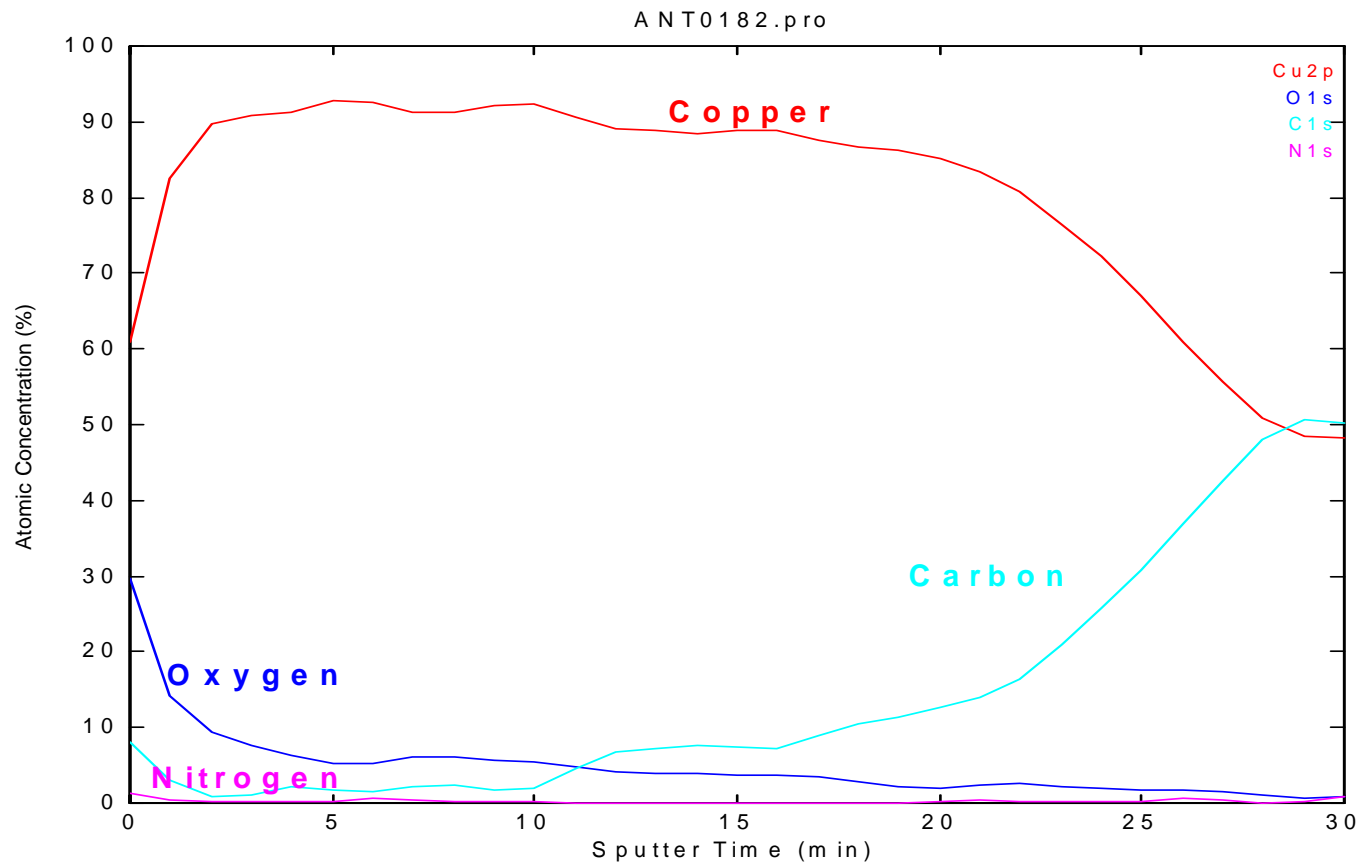
Based on our understanding of the photosintering mechanism, the following know how was developed in order to achieve optimal copper ink for photosintering:

- Narrow size distribution of copper nanoparticles in dispersion;
- Diameter of nanoparticles in dispersion < 100 nm;
- Suitable passivation during copper nanoparticles production;
- Proper selection between wet and dry processes;
- Suitable choice of vehicles and dispersants;
- Correct choice of loading of copper nanoparticles in dispersion;
- Control agglomeration and achieve proper spectral behavior.

Composition of materials in ink

- Formulations have organic and water-based vehicles and proprietary dispersants
- Vehicles have low toxicities
- Physical properties suitable for inkjetting
- In addition to vehicles and dispersants, other additives are included that control viscosity, surface tension, and surface wetting properties.
- Ink formulations optimized for processing by photosintering
- Copper ink photosintered in air at ambient temperature without need for inert gas
- Copper nanoparticles pretreated for maximum compatibility with the ink components
- Inks stored at ambient temperature in air
- Any oxide not removed by additives will be removed during photosintering

Depth profile of XPS for copper film



Piezo-inkjet printers

- Dimatix DMP-2800 series printer
- 16 continuously operating nozzles
- Preliminary data obtained
- Lines are 51mm x 225 microns x 0.1 microns

Image of longitudinal patterns-X100

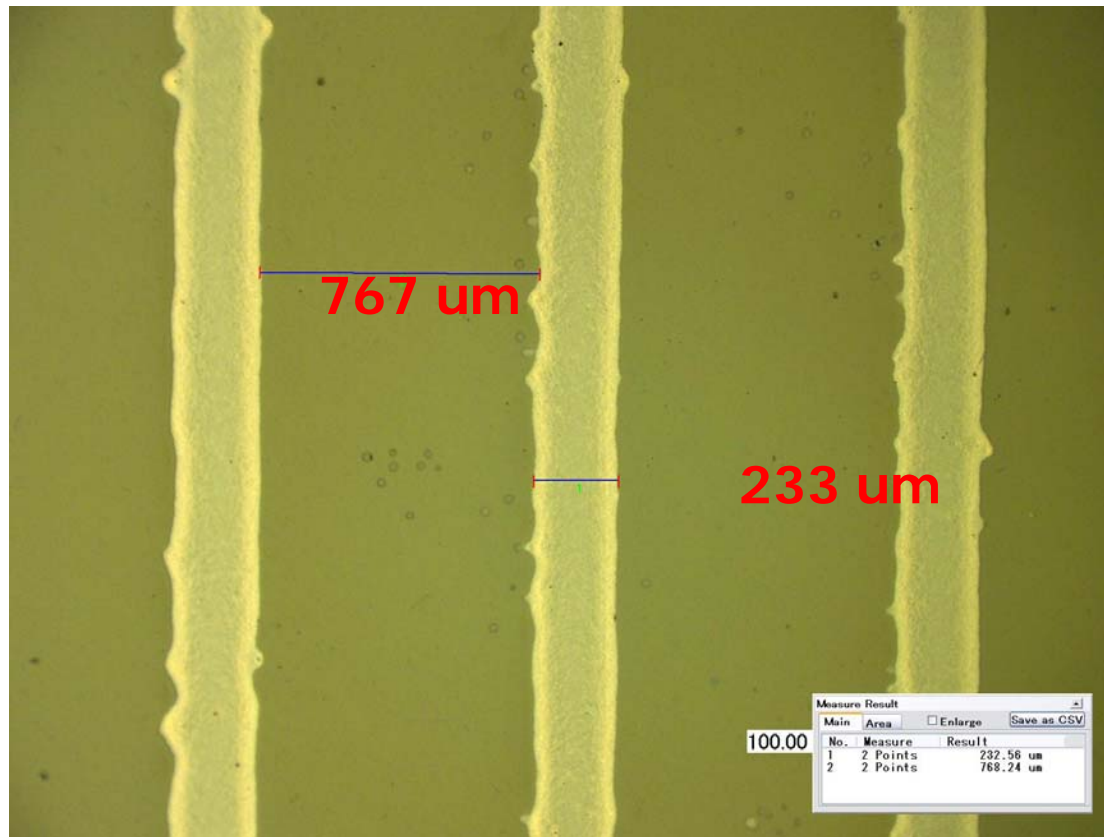
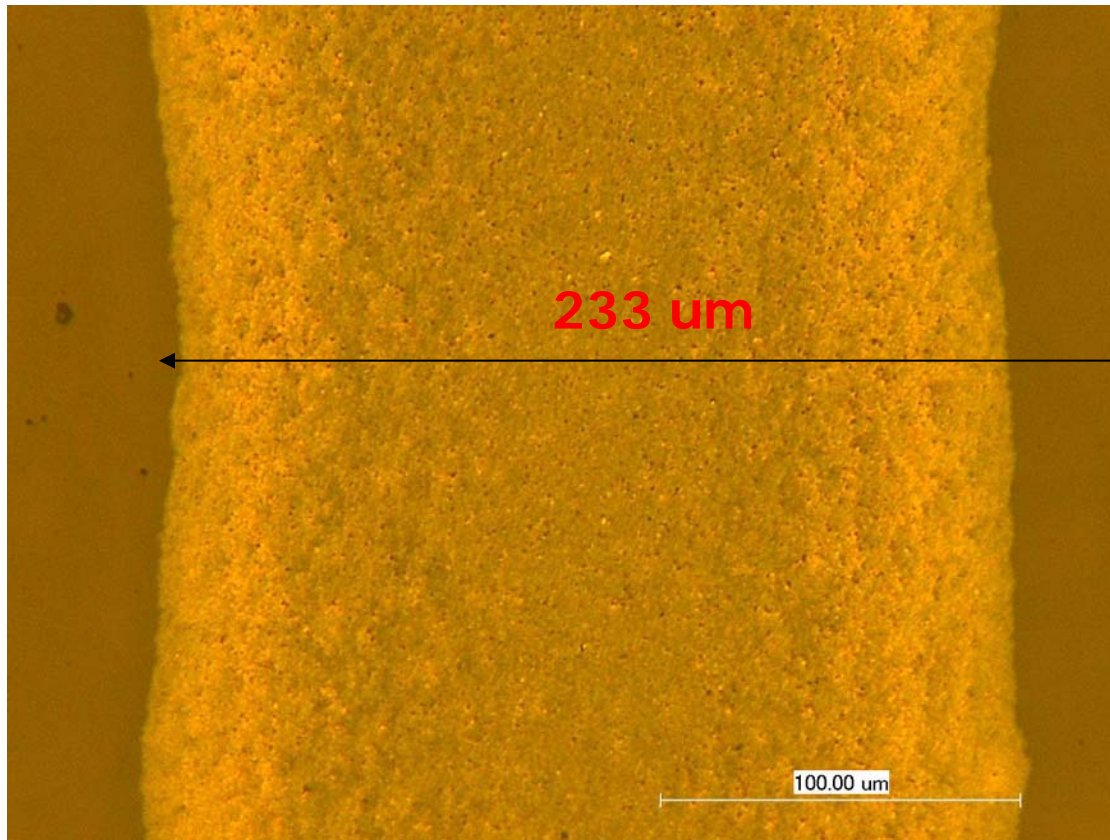
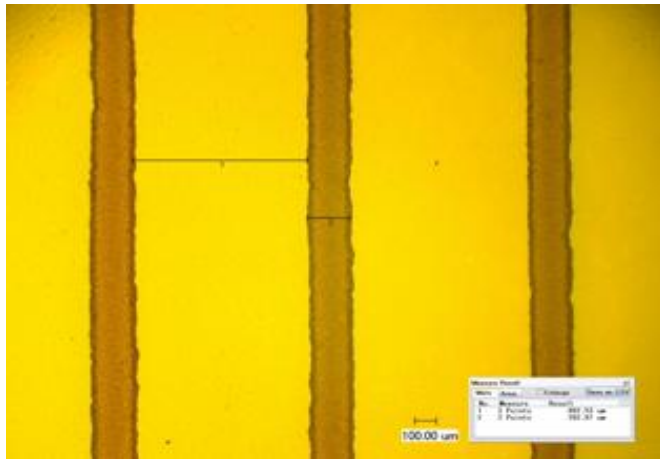


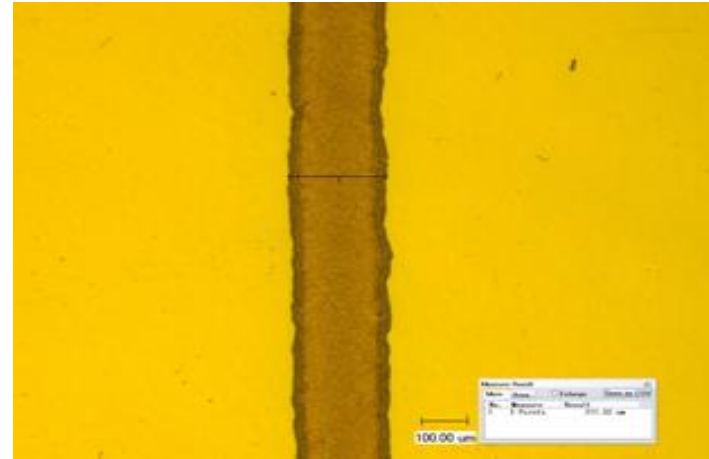
Image of longitudinal patterns- X1000



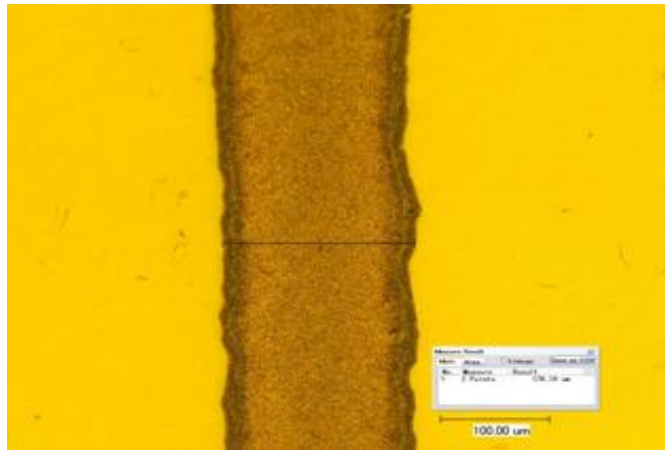
Inkjet line images



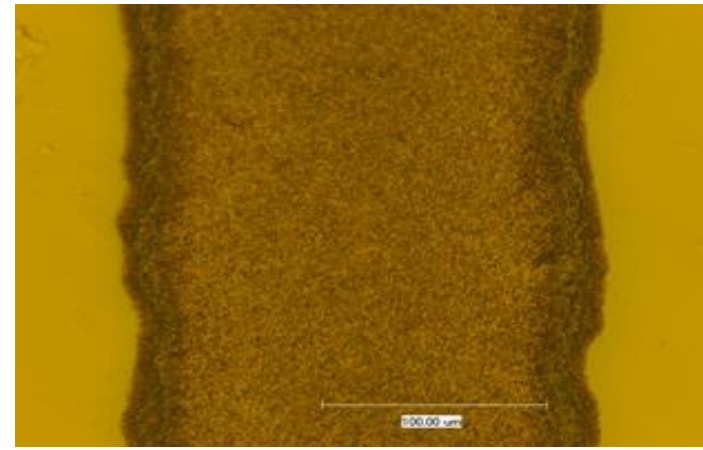
X100



x200

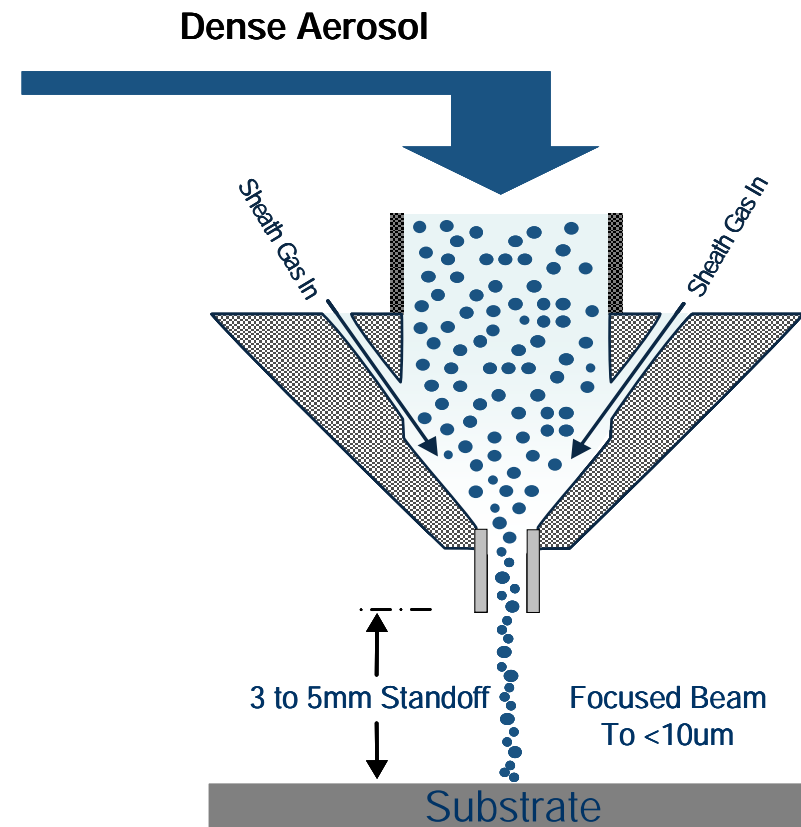
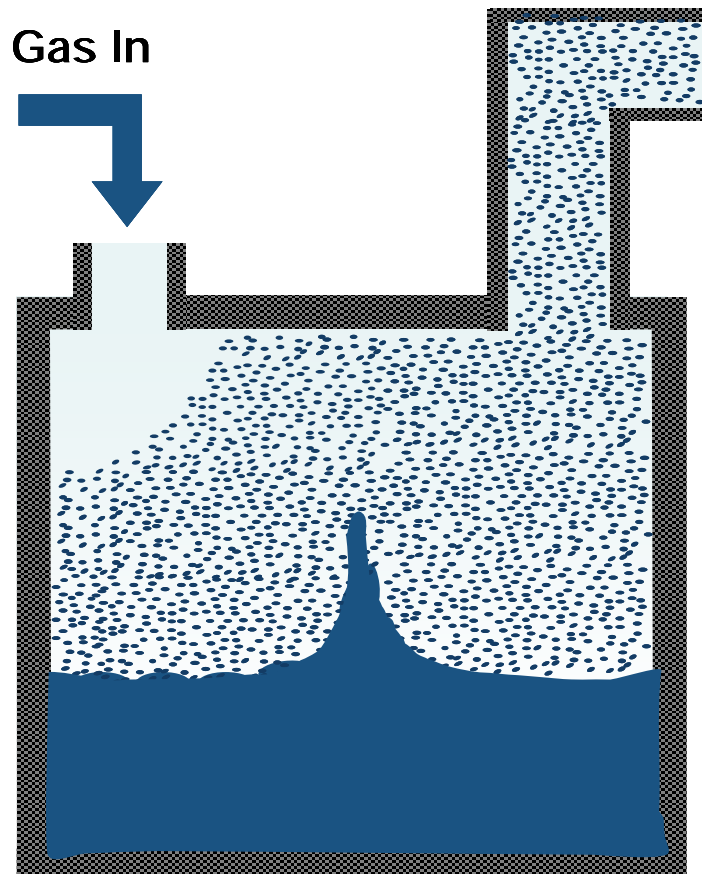


x500



x1000

Optomec aerosol inkjet printer



Panoramic view of ANI's printing laboratory

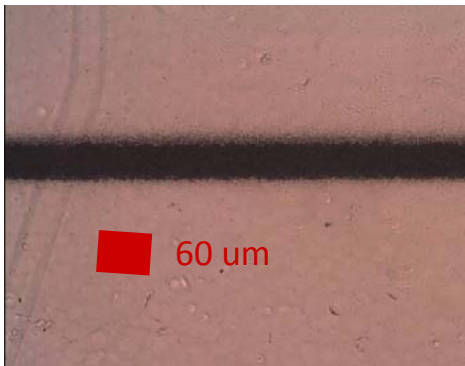


Optomec M³D features

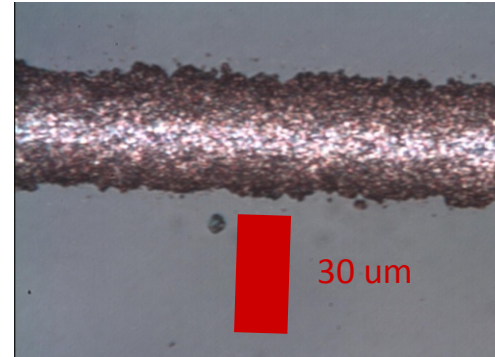
- OPTOMECC[®] M³D[®] printer
- ANI nano-copper ink
- Sintering by OPTOMECC[®] M³D laser light
- Kapton[®] and glass substrates

Optomec/ANI collaboration

- ANI provided its copper nanoparticles inks
- Printing and laser sintering by Optomec M³D
- Substrates: Kapton and glass



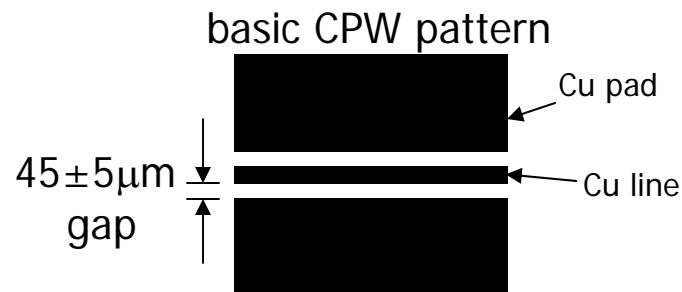
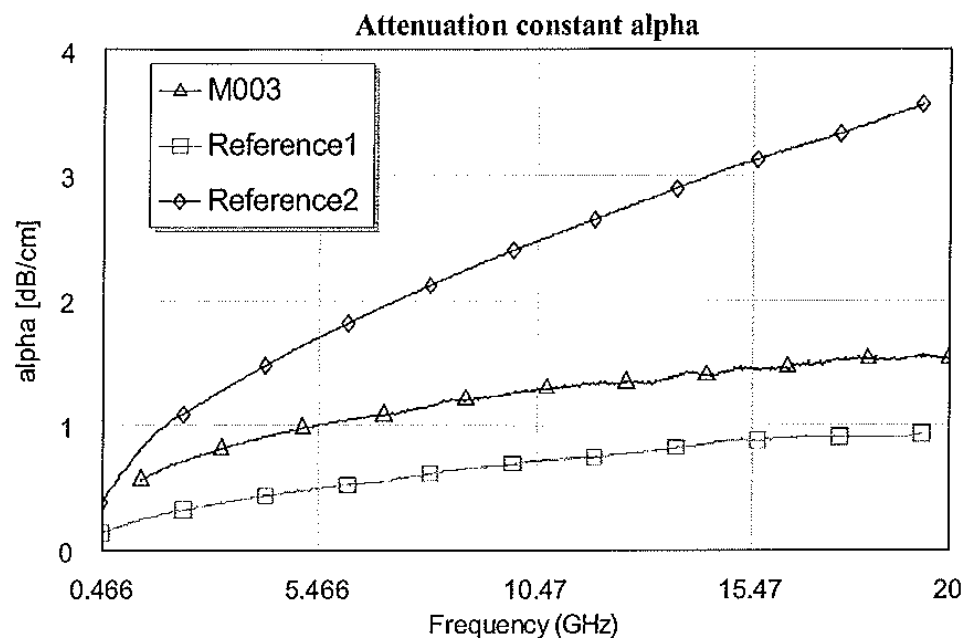
8 μ m thick copper on Kapton



Laser sintered copper ink on glass

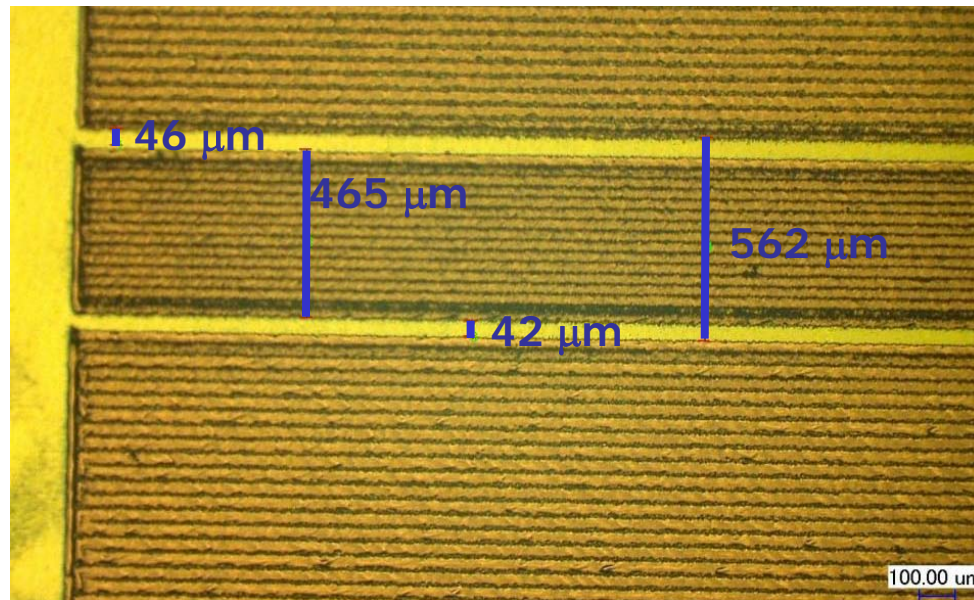
Wide band electrical characterization (RF attenuation)

- ANI's Cu ink
 - prototype ink
 - 1.2 μm thick
- Reference1
 - Ag ink
 - 2.6 μm thick
- Reference2
 - Ag ink
 - 1.2 μm thick



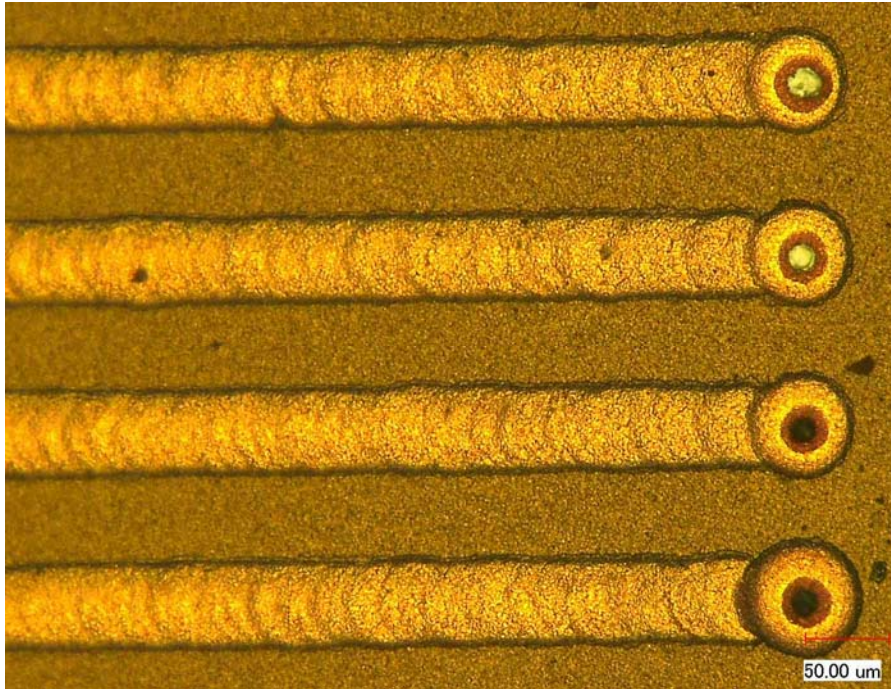
$d_{1/2}(2.5\text{GHz}) = 4 \text{ cm}$
distance for half signal power loss

CPW Cu ink printed using Optomec



* All the attenuation results were obtained at Tampere University of Technology, Prof. Riku Mäkinen group

Laser photosintering of Cu ink on silicon



- Wavelength - 830 nm
- Maximum power - 800 mW
- Laser focus diameter - 15 μm
- Heat spread - $\pm 20 \mu\text{m}$
- Resistivity - 6×10^{-6} Ohm-cm
- Min. line width - 30 μm
- Cu thickness – approx. 2 μm

Conclusions

- ANI achieved a formulation of copper ink that is inkjettable, the temperature of drying is less or equal to 100 degrees C and the photosintering process does not need inert atmosphere.
- Repeatable copper traces are achieved with resistivity of $3 \times 10^{-6} - 4 \times 10^{-6}$ ohm/cm.
- Initial results show that RF attenuation of traces using the copper ink is comparable if not better than traces using Ag ink.
- ANI secured production of copper nanoparticles, in quantities of hundreds of kilograms per month, suitable for the ink production.